

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	 STMicroelectronics International N.V
1.2 PCN No.	AMS/23/14218
1.3 Title of PCN	New Bumping Process for LD39130SJxx products (Power Management BU)
1.4 Product Category	See product list
1.5 Issue date	2023-07-19

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Marcello SAN BIAGIO
2.1.2 Marketing Manager	Salvatore DI VINCENZO
2.1.3 Quality Manager	Giuseppe LISI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	SCS (Stats Chippac Singapore)

4. Description of change

	Old	New
4.1 Description	Printing Bumping Process ASE, Taiwan	Ball Drop Bumping Process SCS (Stats Chippac Singapore)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact on the Electrical, Mechanical, Quality and Reliability Characteristics.	

5. Reason / motivation for change

5.1 Motivation	Following ASE communication about the termination of the current Printing Bumping Process, by DEC 2022, the Power Management BU plans to qualify and implement a New Bumping Process for LDO Devices. The new Bumping process will be implemented in SCS (Stats Chippac Singapore) OSAT. No change to the Package Outline Assembly (mechanical) and electrical characteristics (datasheet). No other change is made with respect to this PCN. Wafer diffusion as well as Testing & Finishing/ DPS remain unchanged both in terms of flow and location
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	The traceability of the new parts will be ensured by physical Die Level and Lot Level codification.
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7. Timing / schedule

7.1 Date of qualification results	2023-07-12
7.2 Intended start of delivery	2023-10-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	14218 13522 RER 1705W2022 LD39130SJ18R LD39130SJ33R WLCSP STS rev1.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-07-19

9. Attachments (additional documentations)
14218 Public product.pdf 14218 13522 RER 1705W2022 LD39130SJ18R LD39130SJ33R WLCSP STS rev1.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	LD39130SJ10R	
	LD39130SJ12R	
	LD39130SJ25R	
	LD39130SJ29R	
	LD39130SJ30R	
	LD39130SJ41R	



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : New Bumping Process for LD39130SJxx products (Power Management BU)

PCN Reference : AMS/23/14218

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

LD39130SJ10R	LD39130SJ30R	LD39130SJ41R
LD39130SJ12R	LD39130SJ29R	LD39130SJ25R

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